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| Form PTO-1449 (REV. 8-83) | | US Dept. of Commerce PATENT & TRADEMARK OFFICE | | ATTY DOCKET NO. 108379 | | APPLICATION NO. 09/761,191 | |
| INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary) <div style="position: absolute; top: 50px; left: 50px; border: 1px solid black; border-radius: 50%; padding: 10px; text-align: center;"> O T P E APR 05 2004 PATENT & TRADEMARK OFFICE </div> | | | | APPLICANT Hiroyuki KUMAKURA | | | |
| | | | | FILING DATE January 18, 2001 | | GROUP 1711 | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| EXAMINER INITIAL | | DOCUMENT NUMBER | DATE | NAME | CLASS | SUB CLASS | |
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| FOREIGN PATENT DOCUMENTS | | | | | | | |
| | | DOCUMENT NUMBER | DATE | COUNTRY | CLASS | SUB CLASS | |
| SMC | 1 | JP A 8-277385 w/Abstract & Translation | 10/22/1996 | Japan | | | |
| SMC | 2 | JP A 8-283379 w/Abstract & Translation | 10/29/1996 | Japan | | | |
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| OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.) | | | | | | | |
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| EXAMINER <i>S. McEllen</i> | | | | DATE CONSIDERED <i>6/7/04</i> | | | |
| Examiner: Initial if citation considered, whether or not citation is in conformance with M.P.E.P. 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. | | | | | | | |

Date: April 5, 2004